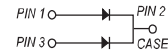
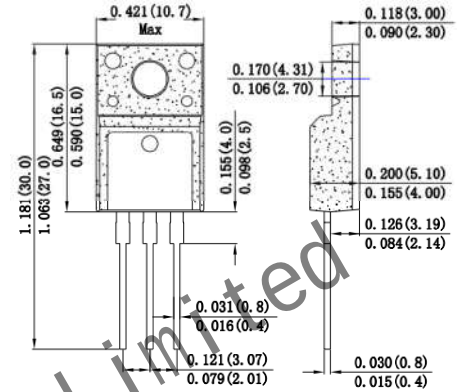


30.0Amp Schottky Barrier Rectifiers
Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- Construction utilizes void-free molded plastic technique
- Low reverse leakage
- High forward surge current capability
- High temperature soldering guaranteed
250°C/10 seconds at terminals

ITO-220AB


Dimensions in inches and (millimeters)

Mechanical Data
Case : Molded plastic body

Terminals : Solder plated, solderable per MIL-STD-750, Method 2026

Polarity : Polarity symbol marking on body

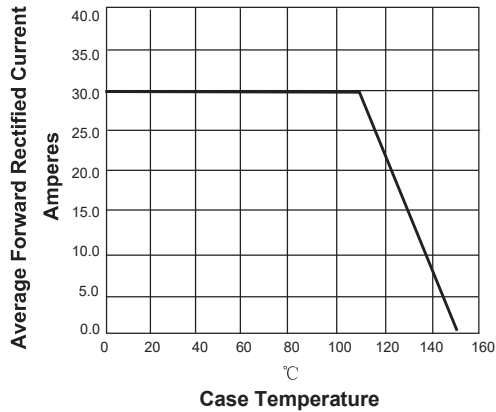
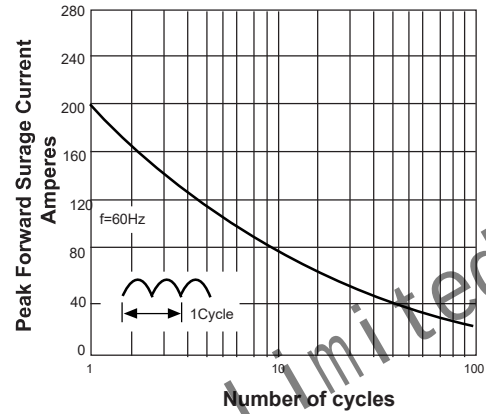
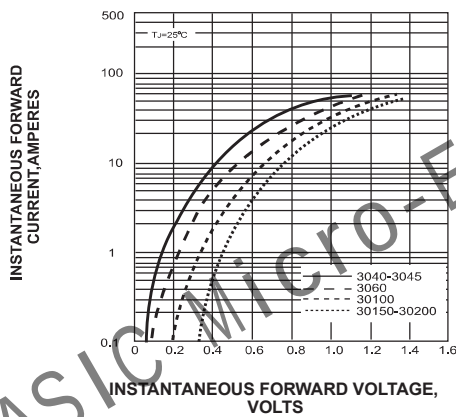
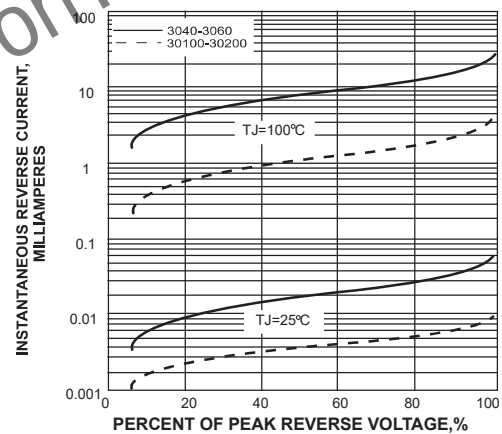
Mounting Position : Any

Maximum Ratings And Electrical Characteristics

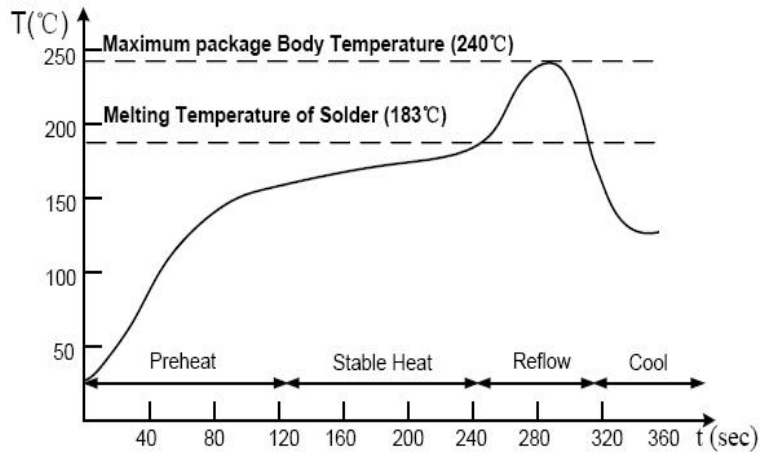
Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	ASBMBR30 40FCTWX0	ASBMBR30 45FCTWX0	ASBMBR30 60FCTWX0	ASBMBR30 100FCTWX0	ASBMBR30 150FCTWX0	ASBMBR30 200FCTWX0	UNITS
Maximum repetitive peak reverse voltage	V _{RRM}	40	45	60	100	150	200	V
Maximum RMS voltage	V _{RMS}	28	31.5	42	70	105	140	V
Maximum DC blocking voltage	V _{DC}	40	45	60	100	150	200	V
Maximum average forward rectified current at T _c =110°C per device per diode	I _(AV)	30.0 15.0						A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I _{FSM}	200.0						A
Maximum instantaneous forward voltage per diode at 15.0A	V _F	0.55		0.70	0.85	0.95		V
Maximum DC reverse current at rated DC blocking voltage T _A =25°C T _A =125°C	I _R	0.5 50			0.05 10			mA
Typical thermal resistance	R _{qjc}	3.5						°C/W
Operating junction temperature range	T _J	-55 to +150						°C
Storage temperature range	T _{STG}	-55 to +150						°C

Ratings And Characteristic Curves

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER LEG

FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS


Suggested Soldering Temperature Profile



Note

- Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
- The device can be exposed to a maximum temperature of 265°C for 10 seconds.
- Devices can be cleaned using standard industry methods and solvents.
- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Tube Package

Package	Tube (mm)	Q'TY/Tube (Kpcs)	Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
ITO	525*31.9*6.4	0.05	545*150*45	1.0	575*245*170	5.0